

Title (en)

Electromagnetic relay and method for its manufacture

Title (de)

Elektromagnetisches Relais und Verfahren zu dessen Herstellung

Title (fr)

Relais électromagnétique et méthode pour sa fabrication

Publication

**EP 0768693 A3 20000412 (DE)**

Application

**EP 96115680 A 19960930**

Priority

DE 19537612 A 19951009

Abstract (en)

[origin: US5929730A] A single or double relay is provided. The relay has a base and a coil body. Each relay has a coil with an axis parallel to the bottom side of the base, an angled yoke and a plate-shaped armature. The armature is connected to a contact spring that is split into two fork-like legs. A contact leg carries a movable contact and a terminal leg that is connected to a spring carrier in the region in front of the movable armature end. With the double relay, the two armatures lie parallel at opposite ends of the base. The design yields a simple assembly with good heat dissipation particularly for a double relay for high switching currents.

IPC 1-7

**H01H 49/00; H01H 50/14; H01H 50/28; H01H 50/60**

IPC 8 full level

**H01H 49/00** (2006.01); **H01H 50/04** (2006.01); **H01H 50/14** (2006.01); **H01H 50/28** (2006.01); **H01H 50/36** (2006.01); **H01H 50/44** (2006.01);  
**H01H 50/56** (2006.01); **H01H 50/58** (2006.01); **H01H 50/60** (2006.01); **H01H 51/06** (2006.01); **H01H 51/20** (2006.01)

CPC (source: EP US)

**H01H 49/00** (2013.01 - EP US); **H01H 50/14** (2013.01 - EP US); **H01H 50/28** (2013.01 - EP US); **H01H 50/60** (2013.01 - EP US);  
**H01H 2011/0087** (2013.01 - EP US); **H01H 2050/049** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)

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DOCDB simple family (publication)

**US 5929730 A 19990727**; AT E210336 T1 20011215; DE 19537612 C1 19970109; DE 59608358 D1 20020117; EP 0768693 A2 19970416;  
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DOCDB simple family (application)

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